

ABSTRACT

A direct and non-destructive method for measuring recess depth in a semiconductor wafer through use of a solvent, comprising:

- a) placing a recessed wafer into a track;
- b) pouring a solvent into the wafer;
- c) commencement of spinning the track-wafer-solvent to recess the solvent into the wafer trench solvent;
- d) subjecting the track-wafer-solvent from step c) to a subsequent spinning step to spin-off any remaining solvent on the surface of the wafer to leave the wafer trench filled with solvent;
- e) weighing the solvent-filled-trench wafer;
- f) subjecting the solvent-filled-trench wafer to heating to remove the solvent; and

weighing the solvent-free wafer to determine the difference in weight, and using the density of the solvent together with the difference in weight to determine the recess depth.